

App. No. 10/511,991
Office Action Dated April 12, 2006

Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application.

Claims 1, 12, 15, and 16 are amended.

Claims 2-9 are canceled.

Listing of Claims:

1. (Currently Amended) A photodetector, comprising:
a semiconductor chip that converts received light to an electric signal; and
a resin body that encapsulates the semiconductor chip,
wherein the photodetector further comprises a protective unit, and
at least a light transmission area, through which the light passes, in a surface of the resin body on
an incident side of the light is covered by the protective unit,

wherein the protective unit comprises:

a plate member that is disposed above the surface of the resin body on the
incident side of the light;

a sealing member that bonds the plate member and the resin body and is located
away from the light transmission area; and

an inert gas comprising nitrogen enclosed in a space surrounded by the surface of
the resin body on the incident side of the light, the plate member and the sealing member.

- 2-9. (Canceled)

10. The photodetector according to claim 1, wherein the resin body comprises an epoxy resin.

11. The photodetector according to claim 1, wherein an absorptance of the light by the resin body is 10% or less.

App. No. 10/511,991
Office Action Dated April 12, 2006

12. (Currently Amended) An optical head device, comprising:

- a light source;
- a condensing unit that receives light emitted from the light source and collects the light onto an optical storage medium; and
- a photodetector that receives light reflected from the optical storage medium and converts the light to an electric signal,

wherein the photodetector, comprises:

- a semiconductor chip that converts received light to an electric signal; and
- a resin body that encapsulates the semiconductor chip,

wherein the photodetector further comprises a protective unit, and

at least a light transmission area, through which the light passes, in a surface of the resin body on an incident side of the light is covered by the protective unit.

wherein the protective unit comprises:

- a plate member that is disposed above the surface of the resin body on the incident side of the light;
- a sealing member that bonds the plate member and the resin body and is located away from the light transmission area; and
- an inert gas comprising nitrogen enclosed in a space surrounded by the surface of the resin body on the incident side of the light, the plate member and the sealing member.

13. The optical head device according to claim 12, wherein in the case where a transmittance of light having a wavelength of λ_1 with respect to the resin body is 10%, a wavelength λ of the light source satisfies a relationship of $\lambda_1 < \lambda < 1.5 \cdot \lambda_1$.

14. The optical head device according to claim 12, wherein the wavelength λ of the light source is in a range of $390 \text{ nm} < \lambda < 420 \text{ nm}$.

App. No. 10/511,991
Office Action Dated April 12, 2006

15. (Currently Amended) An optical information processing device, comprising:

an optical head device that comprises: a light source; a condensing unit that receives light emitted from the light source and collects the light onto an optical storage medium; and a photodetector that receives light reflected from the optical storage medium and converts the light to an electric signal, wherein the photodetector, comprises: a semiconductor chip that converts received light to an electric signal; and a resin body that encapsulates the semiconductor chip, wherein the photodetector further comprises a protective unit, and at least a light transmission area, through which the light passes, in a surface of the resin body on an incident side of the light is covered by the protective unit;

an electric signal processing unit that receives a signal output from the optical head device and outputs a predetermined signal; and

a driving unit that receives the predetermined signal so as to change a position of at least one selected from the optical head device and the condensing unit,

wherein the protective unit comprises:

a plate member that is disposed above the surface of the resin body on the incident side of the light;

a sealing member that bonds the plate member and the resin body and is located away from the light transmission area; and

an inert gas comprising nitrogen enclosed in a space surrounded by the surface of the resin body on the incident side of the light, the plate member and the sealing member.

16. (Currently Amended) An optical information processing method embodied using an optical information processing device that comprises:

an optical head device that comprises: a light source; a condensing unit that receives light emitted from the light source and collects the light onto an optical storage medium; and a photodetector that receives light reflected from the optical storage medium and converts the light to an electric signal, wherein the photodetector, comprises: a semiconductor chip that converts received light to an electric signal; and a resin body that encapsulates the semiconductor chip, wherein the photodetector further comprises a protective unit, and at least a light transmission area, through which the light passes, in a surface of the resin body on an incident side of the light is covered by the protective unit;

App. No. 10/511,991
Office Action Dated April 12, 2006

an electric signal processing unit that receives a signal output from the optical head device and outputs a predetermined signal; and

a driving unit that receives the predetermined signal so as to change a position of at least one selected from the optical head device and the condensing unit,

wherein in the case where a transmittance of light having a wavelength of λ_1 with respect to the resin body is 10%, a wavelength λ of the light source satisfies a relationship of $\lambda_1 < \lambda < 1.5 \cdot \lambda_1$,

wherein the protective unit comprises:

a plate member that is disposed above the surface of the resin body on the incident side of the light;

a sealing member that bonds the plate member and the resin body and is located away from the light transmission area; and

an inert gas comprising nitrogen enclosed in a space surrounded by the surface of the resin body on the incident side of the light, the plate member and the sealing member.

17. The information processing method according to claim 16, wherein the light source emits light having a wavelength λ of $390 \text{ nm} < \lambda < 420 \text{ nm}$.